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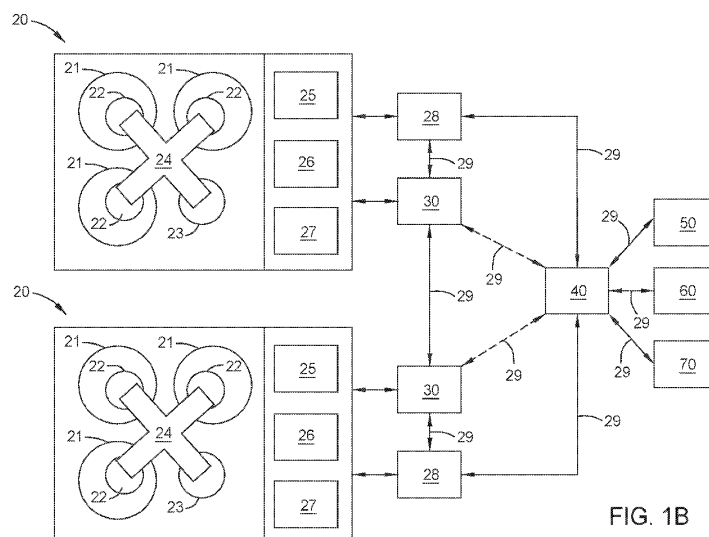
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(54) **Title:** ADAPTIVE SLURRY DISPENSE SYSTEM

(S7) Abstract: Provided herein are advanced substrate polishing methods that use a machine learning artificial intelligence (AI) algorithm, or a software application generated using the AI, to control one or more aspects of the polishing process. The AI algorithm is trained to simulate a polishing process and to make predictions about the polishing process and process results expected therefrom, using substrate processing data acquired from a polishing system.

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